

Absolute Maximum Ratings

Parameter	Rating	Units
Peak Pulse Current (8/20μs)	150	A
Peak Pulse Power (8/20μs)	3300	W
IEC 61000-4-2, Direct Discharge, (Level 4)	30	kV
IEC 61000-4-2, Air Discharge, (Level 4)	30	kV
IEC 61000-4-5 (8/20μs)	150	A
Telcordia GR 1089 (Intra-Building) (2/10μs)	100	A
ITU K.20 (5/310μs)	40	A

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

Parameter	Rating	Units
SOIC Package	170	°C/W
Operating Temperature Range	-40 to 125	°C
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s) (SOIC - Lead Tips Only)	260	°C

Electrical Characteristics (T_{OP} = 25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Stand-Off Voltage	V _{RWM}	I _T ≤ 1μA	-	-	3.3	V
Reverse Breakdown Voltage	V _{BR}	I _T = 2μA	3.3	-	-	V
Snap Back Voltage	V _{SB}	I _T = 50mA	3.3	-	-	V
Reverse Leakage Current	I _R	V _{RWM} = 3.3V, T = 25°C	-	-	1	μA
Clamping Voltage, Line-Ground	V _C	I _{pp} = 50A, t _p = 8/20 μs	-	-	13	V
Clamping Voltage, Line-Ground	V _C	I _{pp} = 100A, t _p = 8/20 μs	-	-	17	V
Dynamic Resistance, Line-Ground	R _{DYN}	(V _{C2} - V _{C1}) / (I _{pp2} - I _{pp1})	-	0.15	-	□
Clamping Voltage, Line-Line	V _C	I _{pp} = 50A, t _p = 8/20 μs	-	-	15	V
Clamping Voltage, Line-Line	V _C	I _{pp} = 100A, t _p = 8/20 μs	-	-	20	V
Dynamic Resistance, Line-Line	R _{DYN}	(V _{C2} - V _{C1}) / (I _{pp2} - I _{pp1})	-	0.25	-	□
Junction Capacitance	C _j	Between I/O Pins and Ground V _R = 0V, f = 1MHz	-	9	12	pF
		Between I/O Pins V _R = 0V, f = 1MHz	-	4.5	6	pF

Figure 1: Non-repetitive Peak Pulse Current vs. Pulse Time

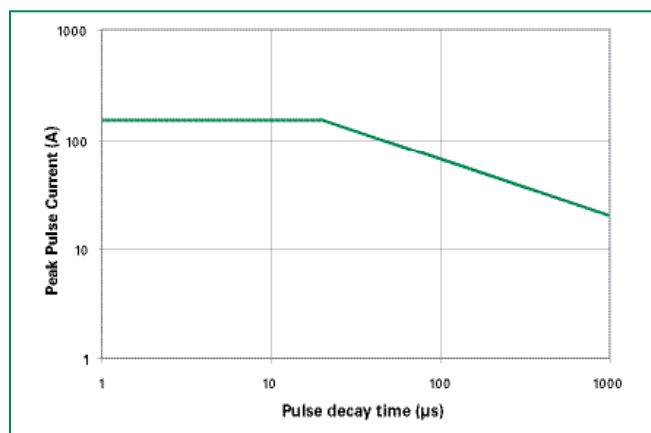


Figure 2: Current Derating Curve

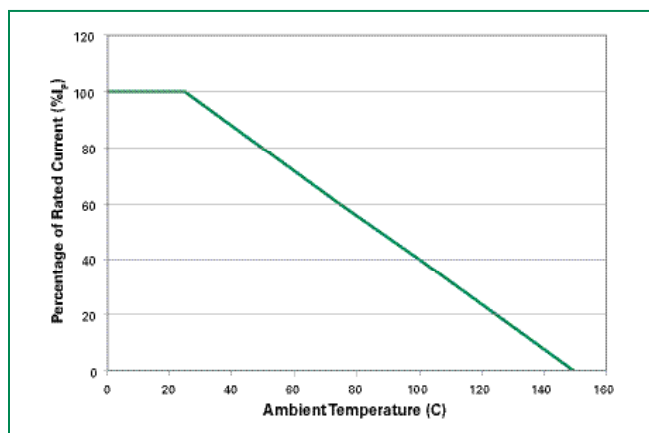


Figure 3: 8/20 μ s Pulse Waveform

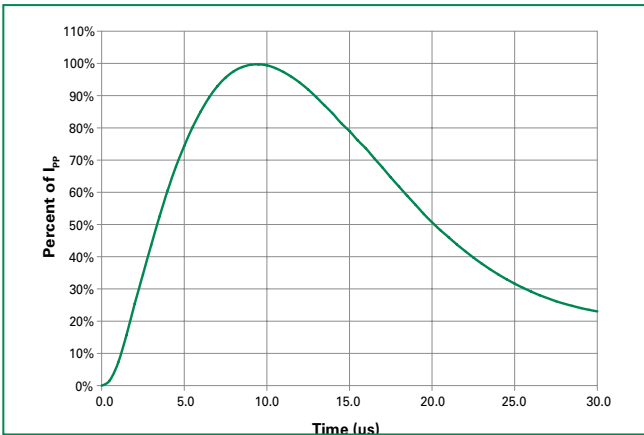


Figure 4: Clamp Voltage vs. Peak Pulse Current

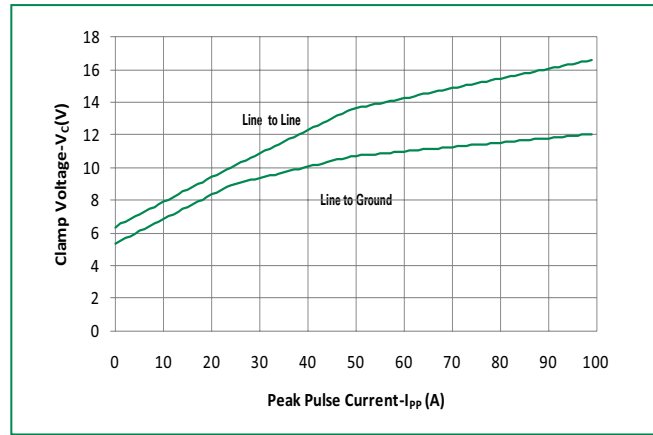


Figure 5: Capacitance vs. Reverse Voltage

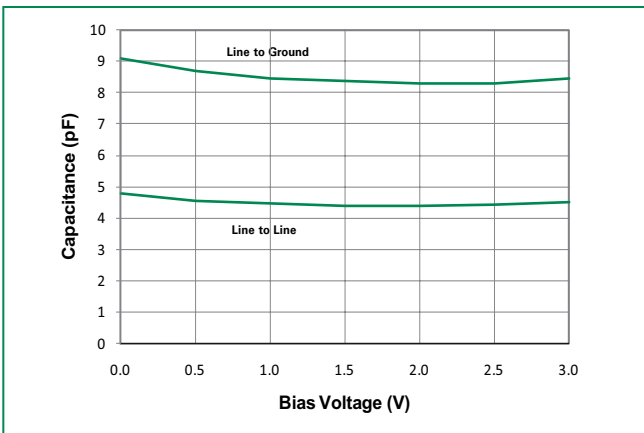
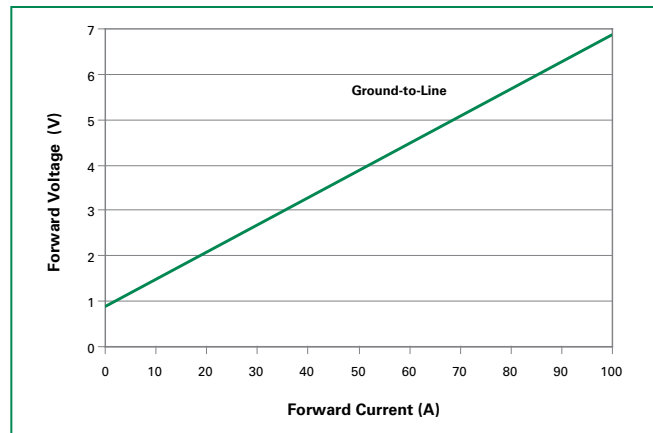
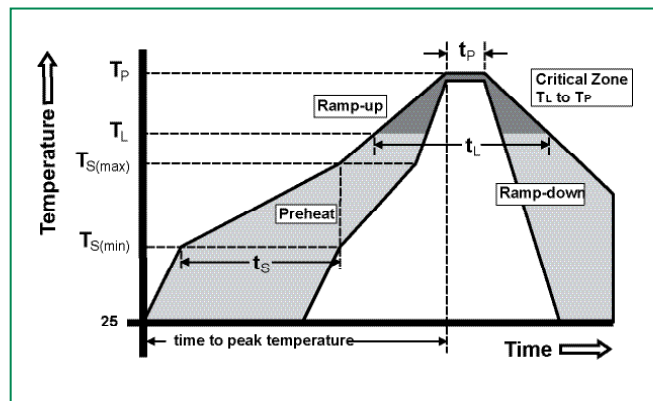


Figure 6: Forward Voltage vs. Forward Current

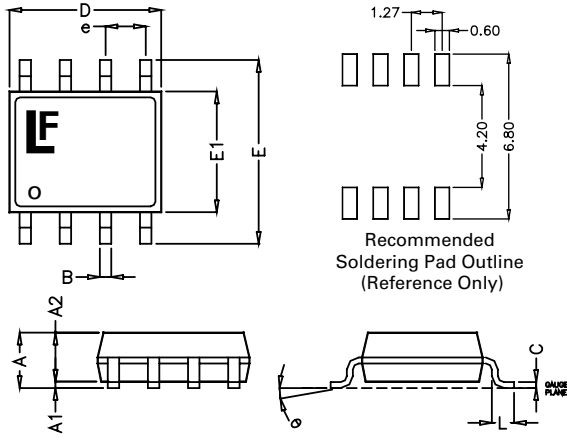


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

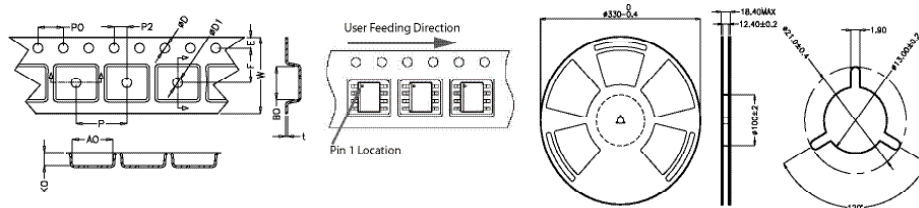


Package Dimensions – Mechanical Drawings and Recommended Solder Pad Outline



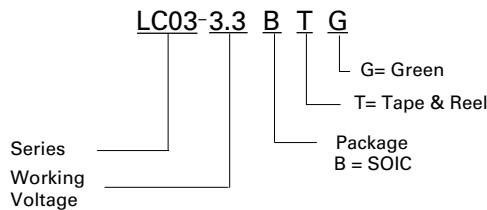
Package	SOIC-8			
Pins	8			
JEDEC	MS-012			
	Millimetres		Inches	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	1.65	0.050	0.065
B	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
L	0.40	1.27	0.016	0.050

Embossed Carrier Tape & Reel Specification – SOIC Package

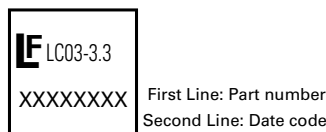


	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.065	0.073
F	5.4	5.6	0.213	0.22
P2	1.95	2.05	0.077	0.081
D	1.5	1.6	0.059	0.063
D1	1.50 Min		0.059 Min	
P0	3.9	4.1	0.154	0.161
10P0	40.0 ± 0.20		1.574 ± 0.008	
W	11.9	12.1	0.468	0.476
P	7.9	8.1	0.311	0.319
A0	6.3	6.5	0.248	0.256
B0	5.1	5.3	0.2	0.209
K0	2	2.2	0.079	0.087
t	0.30 ± 0.05		0.012 ± 0.002	

Part Numbering System



Part Marking System



Ordering Information

Part Number	Package	Marking	Min. Order Qty.
LC03-3.3BTG	SOIC-8	LC03-3.3	2500

Product Characteristics

Lead Plating	Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :

- All dimensions are in millimeters
- Dimensions include solder plating.
- Dimensions are exclusive of mold flash & metal burr.
- Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
- Package surface matte finish VDI 11-13.

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